

Mobile DRAM Stack Code Information(1/3)

Last Updated : April 2009

K 3 X X X X X X X X - X X X X X X X

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. Mobile DRAM Stack : 3

3. Small Classification

A : MDDR + MSDR + Interposer

B : MDDR + MSDR

C : MDDR + MDDR + Interposer

D : MDDR + MDDR

E : MDDR + MDDR + MDDR

P : MDDR2-P(*S4)+MDDR2-P(*S4)

4~5. A-Port I/F & Density & Vcc & Org.

Code	I/F	Den	VDD 1	VDD 2	VD DQ	VDD CA	Org	Opt
00	NONE							
01	MDDR	512M b	1.8	-	1.8	-	x3 2	-
02	MDDR	1Gb	1.8	-	1.8	-	x3 2	-
03	MDDR	1Gb+ 512M b	1.8	-	1.8	-	x3 2	-
04	MDDR	1Gb+ 1Gb	1.8	-	1.8	-	x3 2	-
A2	MDDR	1Gb	1.8	-	1.8	-	x3 2	PE A
C2	MDDR2 -P	512M b	1.8	1.3 5	1.2	1.2	x3 2	-
C3	MDDR2 -P	1Gb	1.8	1.3 5	1.2	1.2	x3 2	-
E3	MDDR2 -P	1Gb	1.8	1.2	1.2	1.2	x3 2	-

6~7. B-Port I/F & Density & Vcc & Org.

Code	I/F	Den	VDD 1	VDD 2	VD DQ	VDD CA	Org	Opt
00	NONE							
01	MSDR	128M	1.8	-	1.8	-	x3 2	-
02	MSDR	256M	1.8	-	1.8	-	x3 2	-
03	MDDR	1Gb	1.8	-	1.8	-	x3 2	-
04	MDDR	512M b	1.8	-	1.8	-	x3 2	-
05	MDDR	256M b	1.8	-	1.8	-	x3 2	-
A3	MDDR	1Gb	1.8	-	1.8	-	x3 2	PE A
A4	MDDR	512M b	1.8	-	1.8	-	x3 2	PE A
C2	MDDR2 -P	512M b	1.8	1.3 5	1.2	1.2	x3 2	-
C3	MDDR2 -P	1Gb	1.8	1.3 5	1.2	1.2	x3 2	-
E3	MDDR2 -P	1Gb	1.8	1.2	1.2	1.2	x3 2	-

8. Reserved

0 : 0

9. Interposer I/F

0 : NONE

1 : KYM000100M

10. Generation

M : M-die

A : A-die

B : B-die

C : C-die

D : D-die

E : E-die

F : F-die

G : G-die

Mobile DRAM Stack Code Information(2/3)

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K	3	X	X	X	X	X	X	X	X	-	X	X	X	X	X	X	
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

11. "—"

12. Package

F : FBGA D : FBGA (Lead-Free)
P : FBGA (Lead-Free, Halogen-Free, OSP)
 S : 176-FBGA (Lead-Free, Halogen-Free)

13. Temp.

G : -25 ~ 85 °C X : -25 ~ 105 °C

14~15. Speed

00 : NONE C3 : 7.5ns@CL3
 C6 : 6ns@CL3

* MDDR2-P(※S4)+MDDR2-P(※S4)

C6 : 6.0ns@RL3, TRCD18ns, TRP18ns
 C8 : 5.0ns@RL3, TRCD18ns, TRP18ns
 C9 : 3.75ns@RL4, TRCD18ns, TRP18ns
 C0 : 3.0ns@RL5, TRCD18ns, TRP18ns
 C1 : 2.5ns@RL6, TRCD18ns, TRP18ns
 D6 : 6.0ns@RL3, TRCD15ns, TRP15ns
 D8 : 5.0ns@RL3, TRCD15ns, TRP15ns
 D9 : 3.75ns@RL4, TRCD15ns, TRP15ns
 D0 : 3.0ns@RL5, TRCD15ns, TRP15ns
 D1 : 2.5ns@RL6, TRCD15ns, TRP15ns

Mobile DRAM Stack Code Information(3/3)

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<u>K</u>	<u>3</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

16. Packing “Packing Type Reference”

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer “Customer List Reference”